

54F153,74F153

54F153 74F153 Dual 4-Input Multiplexer



Literature Number: SNOS156A

54F/74F153 Dual 4-Input Multiplexer

General Description

The 'F153 is a high-speed dual 4-input multiplexer with common select inputs and individual enable inputs for each section. It can select two lines of data from four sources. The two buffered outputs present data in the true (non-inverted)

form. In addition to multiplexer operation, the 'F153 can generate any two functions of three variables.

Features

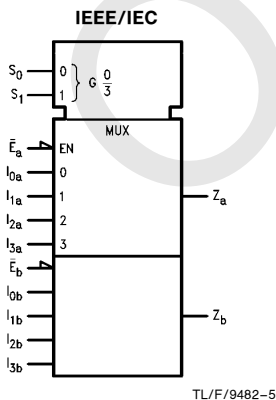
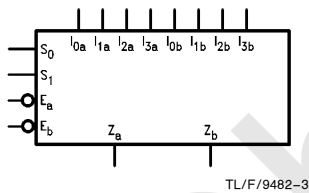
- Guaranteed 4000V minimum ESD protection

Commercial	Military	Package Number	Package Description
74F153PC		N16E	16-Lead (0.300" Wide) Molded Dual-In-Line
	54F153DM (Note 2)	J16A	16-Lead Ceramic Dual-In-Line
74F153SC (Note 1)		M16A	16-Lead (0.150" Wide) Molded Small Outline, JEDEC
74F153SJ (Note 1)		M16D	16-Lead (0.300" Wide) Molded Small Outline, EIAJ
	54F153FM (Note 2)	W16A	16-Lead Cerpack
	54F153LM (Note 2)	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C

Note 1: Devices also available in 13" reel. Use suffix = SCX and SJX.

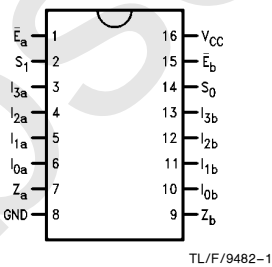
Note 2: Military grade device with environmental and burn-in processing. Use suffix = DMOB, FMOB and LMOB.

Logic Symbols

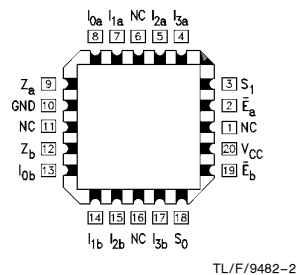


Connection Diagrams

Pin Assignment
for DIP, SOIC and Flatpak



Pin Assignment
for LCC



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Unit Loading/Fan Out

Pin Names	Description	54F/74F	
		U.L. HIGH/LOW	Input I _{IH} /I _{IL} Output I _{OH} /I _{OL}
I _{0a} -I _{3a}	Side A Data Inputs	1.0/1.0	20 μA/ -0.6 mA
I _{0b} -I _{3b}	Side B Data Inputs	1.0/1.0	20 μA/ -0.6 mA
S ₀ , S ₁	Common Select Inputs	1.0/1.0	20 μA/ -0.6 mA
\bar{E}_a	Side A Enable Input (Active LOW)	1.0/1.0	20 μA/ -0.6 mA
\bar{E}_b	Side B Enable Input (Active LOW)	1.0/1.0	20 μA/ -0.6 mA
Z _a	Side A Output	50/33.3	-1 mA/20 mA
Z _b	Side B Output	50/33.3	-1 mA/20 mA

Functional Description

The 'F153 is a dual 4-input multiplexer. It can select two bits of data from up to four sources under the control of the common Select inputs (S₀, S₁). The two 4-input multiplexer circuits have individual active LOW Enables (\bar{E}_a , \bar{E}_b) which can be used to strobe the outputs independently. When the Enables (\bar{E}_a , \bar{E}_b) are HIGH, the corresponding outputs (Z_a, Z_b) are forced LOW. The 'F153 is the logic implementation of a 2-pole, 4-position switch, where the position of the switch is determined by the logic levels supplied to the two Select inputs. The logic equations for the outputs are as follows:

$$Z_a = \bar{E}_a \cdot (I_{0a} \cdot \bar{S}_1 \cdot \bar{S}_0 + I_{1a} \cdot \bar{S}_1 \cdot S_0 + I_{2a} \cdot S_1 \cdot \bar{S}_0 + I_{3a} \cdot S_1 \cdot S_0)$$

$$Z_b = \bar{E}_b \cdot (I_{0b} \cdot \bar{S}_1 \cdot \bar{S}_0 + I_{1b} \cdot \bar{S}_1 \cdot S_0 + I_{2b} \cdot S_1 \cdot \bar{S}_0 + I_{3b} \cdot S_1 \cdot S_0)$$

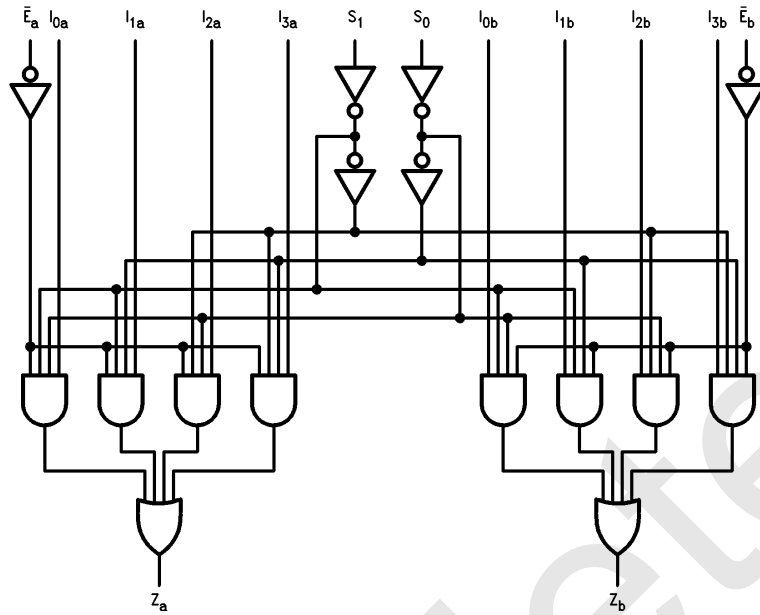
The 'F153 can be used to move data from a group of registers to a common output bus. The particular register from which the data came would be determined by the state of the Select inputs. A less obvious application is as a function generator. The 'F153 can generate two functions of three variables. This is useful for implementing highly irregular random logic.

Truth Table

Select Inputs		Inputs (a or b)					Output
S ₀	S ₁	\bar{E}	I ₀	I ₁	I ₂	I ₃	Z
X	X	H	X	X	X	X	L
L	L	L	L	X	X	X	L
L	L	L	H	X	X	X	H
H	L	L	X	L	X	X	L
H	L	L	X	H	X	X	H
L	H	L	X	X	L	X	L
L	H	L	X	X	H	X	H
H	H	L	X	X	X	L	L
H	H	L	X	X	X	H	H

H = HIGH Voltage Level
L = LOW
X = Immaterial

Logic Diagram



TL/F/9482-4

Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Storage Temperature	–65°C to +150°C
Ambient Temperature under Bias	–55°C to +125°C
Junction Temperature under Bias	–55°C to +175°C
Plastic	–55°C to +150°C
V _{CC} Pin Potential to Ground Pin	–0.5V to +7.0V
Input Voltage (Note 2)	–0.5V to +7.0V
Input Current (Note 2)	–30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V _{CC} = 0V)	
Standard Output	–0.5V to V _{CC}
TRI-STATE® Output	–0.5V to +5.5V

Current Applied to Output in LOW State (Max) twice the rated I_{OL} (mA)

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

Free Air Ambient Temperature	
Military	–55°C to +125°C
Commercial	0°C to +70°C
Supply Voltage	
Military	+4.5V to +5.5V
Commercial	+4.5V to +5.5V

DC Electrical Characteristics

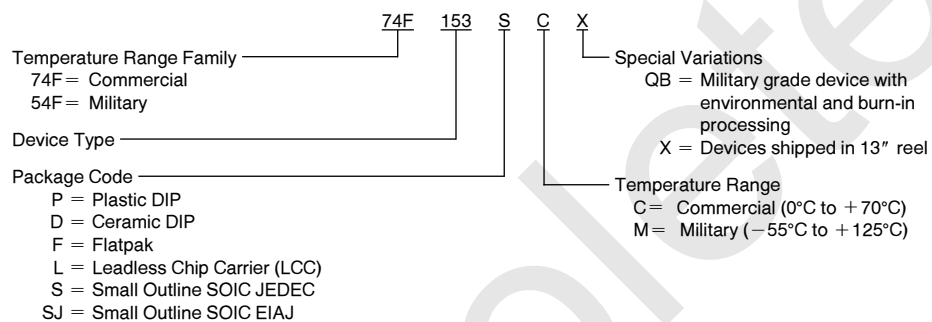
Symbol	Parameter	54F/74F			Units	V _{CC}	Conditions
		Min	Typ	Max			
V _{IH}	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V _{IL}	Input LOW Voltage	0.8			V		Recognized as a LOW Signal
V _{CD}	Input Clamp Diode Voltage	–1.2			V	Min	I _{IN} = –18 mA
V _{OH}	Output HIGH Voltage	54F 10% V _{CC}	2.5		V	Min	I _{OH} = –1 mA
		74F 10% V _{CC}	2.5				I _{OH} = –1 mA
		74F 5% V _{CC}	2.7				I _{OH} = –1 mA
V _{OL}	Output LOW Voltage	54F 10% V _{CC}		0.5	V	Min	I _{OL} = 20 mA
		74F 10% V _{CC}		0.5			I _{OL} = 20 mA
I _{IH}	Input HIGH Current	54F		20.0	μA	Max	V _{IN} = 2.7V
		74F		5.0			
I _{BVI}	Input HIGH Current Breakdown Test	54F		100	μA	Max	V _{IN} = 7.0V
		74F		7.0			
I _{CEX}	Output High Leakage Current	54F		250	μA	Max	V _{OUT} = V _{CC}
		74F		50			
V _{ID}	Input Leakage Test	74F	4.75		V	0.0	I _{ID} = 1.9 μA All Other Pins Grounded
I _{OD}	Output Leakage Circuit Current	74F		3.75	μA	0.0	V _{IOD} = 150 mV All Other Pins Grounded
I _{IL}	Input LOW Current			–0.6	mA	Max	V _{IN} = 0.5V
I _{OS}	Output Short-Circuit Current		–60	–150	mA	Max	V _{OUT} = 0V
I _{CC1}	Power Supply Current		12	20	mA	Max	V _O = LOW

AC Electrical Characteristics

Symbol	Parameter	74F			54F		74F		Units
		T _A = +25°C V _{CC} = +5.0V C _L = 50 pF			T _A , V _{CC} = Mil C _L = 50 pF		T _A , V _{CC} = Com C _L = 50 pF		
		Min	Typ	Max	Min	Max	Min	Max	
t _{PLH} t _{PHL}	Propagation Delay S _n to Z _n	4.5 3.5	8.1 7.0	10.5 9.0	4.5 3.5	14.0 11.0	4.5 3.5	12.0 10.5	ns
t _{PLH} t _{PHL}	Propagation Delay E _n to Z _n	4.5 3.0	7.1 5.7	9.0 7.0	4.5 2.5	11.5 9.0	4.5 2.5	10.5 8.0	ns
t _{PLH} t _{PHL}	Propagation Delay I _n to Z _n	3.0 2.5	5.3 5.1	7.0 6.5	2.5 2.5	9.0 8.0	3.0 2.5	8.0 7.5	ns

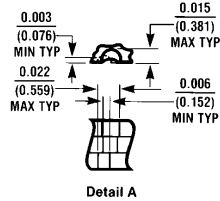
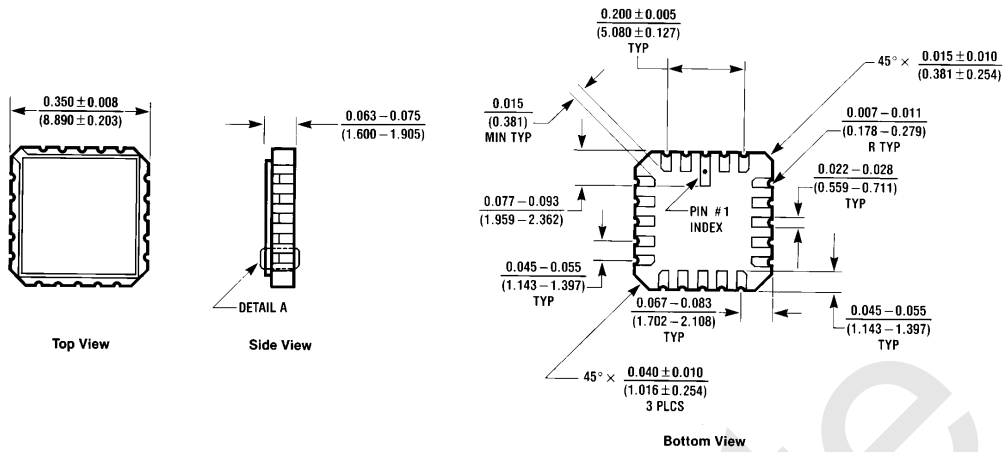
Ordering Information

The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows:



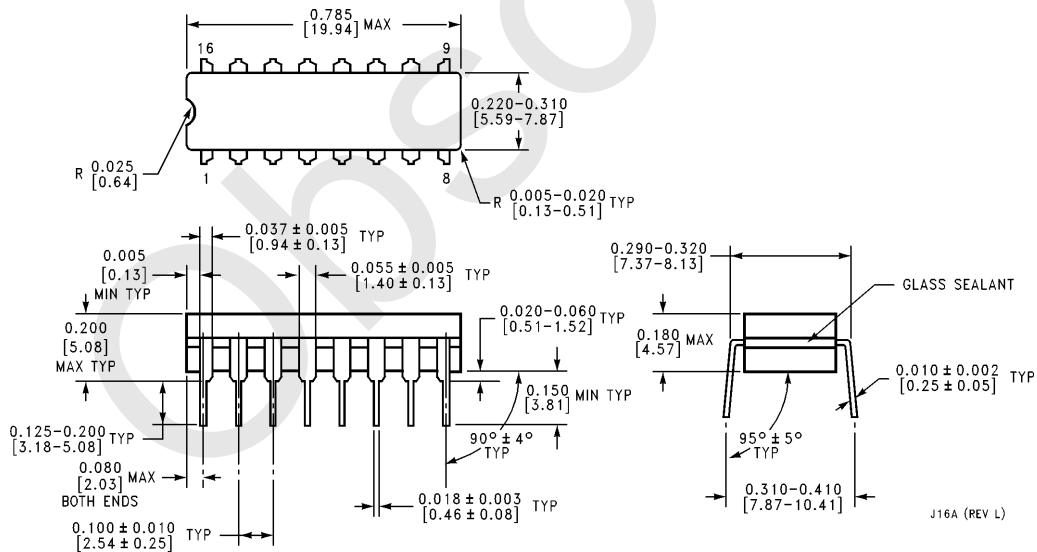
Obsolete

Physical Dimensions inches (millimeters)



20-Lead Ceramic Leadless Chip Carrier (L)
NS Package Number E20A

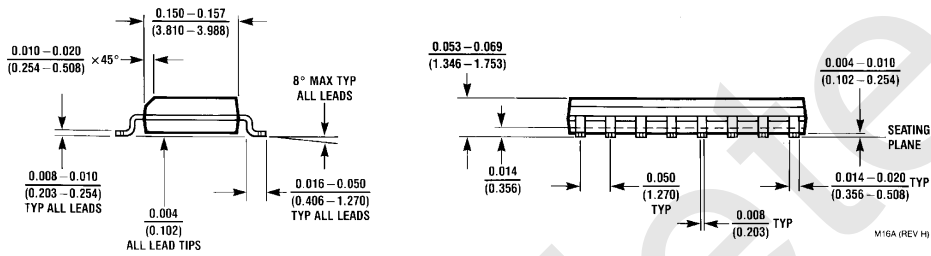
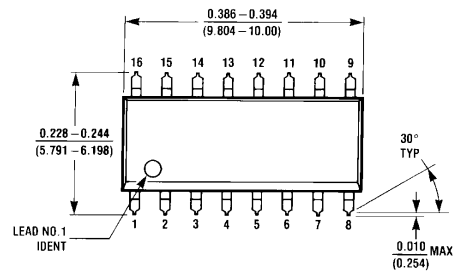
E20A (REV D)



16-Lead Ceramic Dual-In-Line Package (D)
NS Package Number J16A

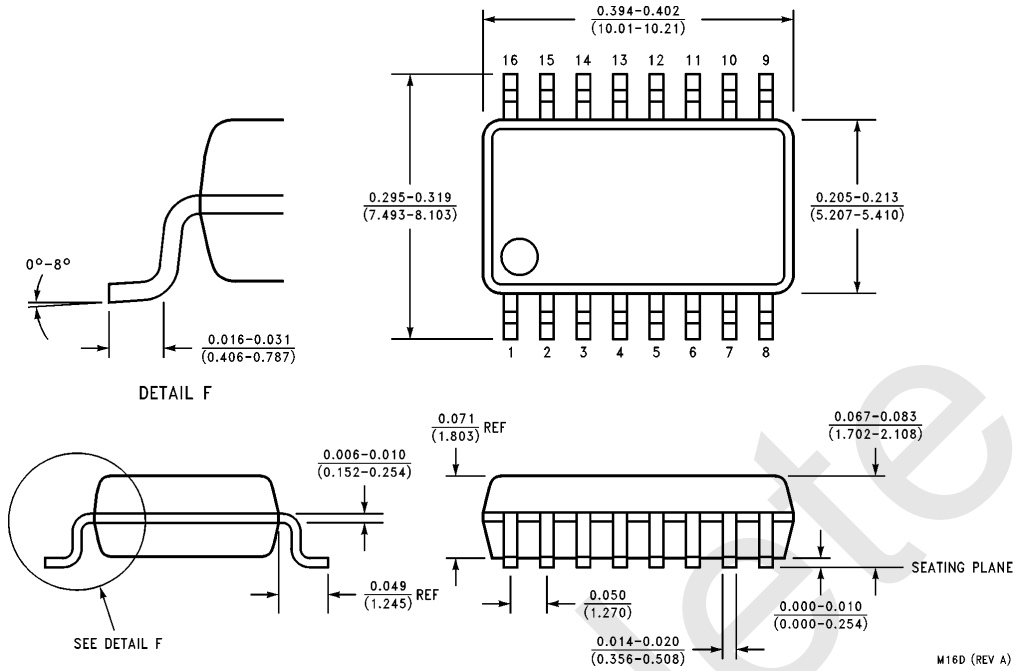
J16A (REV L)

Physical Dimensions inches (millimeters) (Continued)



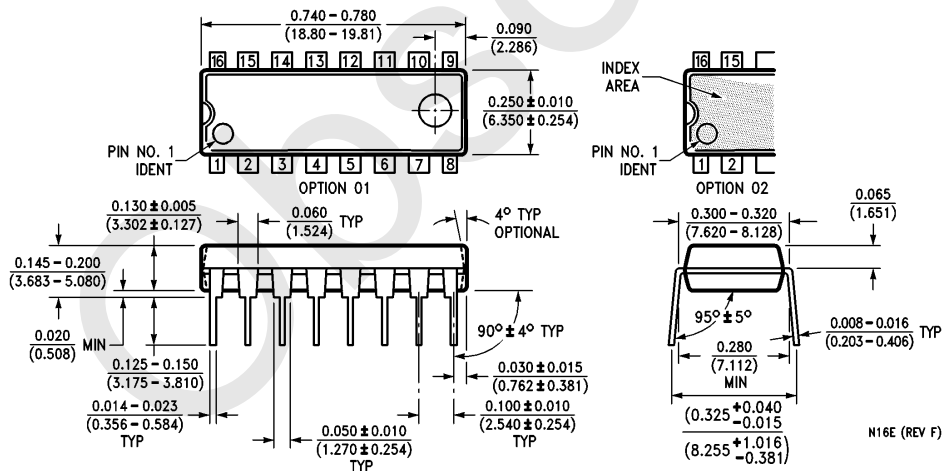
**16-Lead (0.150" Wide) Molded Small Outline Package, JEDEC (S)
NS Package Number M16A**

Physical Dimensions inches (millimeters) (Continued)



16-Lead (0.300" Wide) Molded Small Outline Package, EIAJ (SJ)
NS Package Number M16D

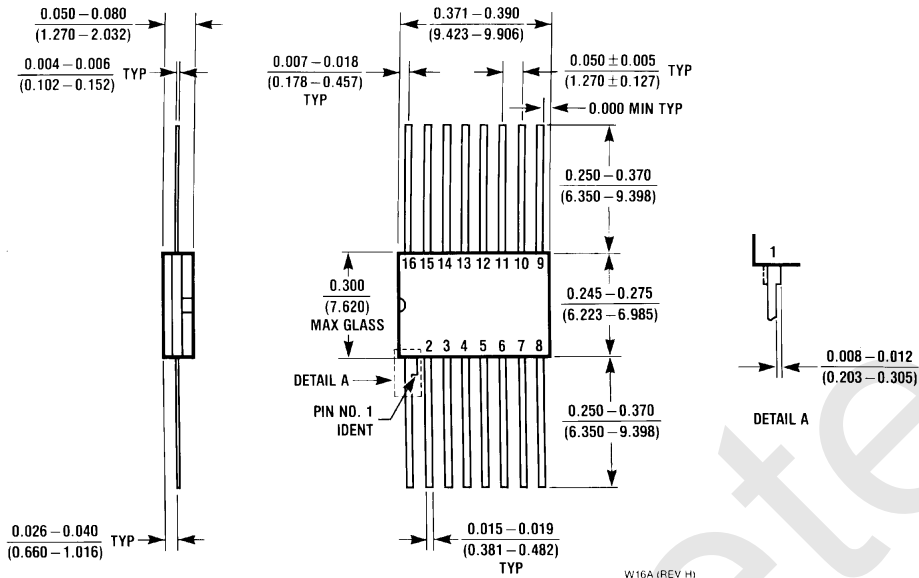
M16D (REV A)



16-Lead (0.300" Wide) Molded Dual-In-Line Package (P)
NS Package Number N16E

N16E (REV F)

Physical Dimensions inches (millimeters) (Continued)



**16-Lead Ceramic Flatpak (F)
NS Package Number W16A**

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